



Material Content Data Sheet



Sales Product Name		BTS7002-1EPP		Issued		4. July 2019		
MA#		MA002587646						
Package		PG-TSDSO-14-22		Weight*		65.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.192	3.35	3.35	33473	33473
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.038	0.06		576	
	non noble metal	iron	7439-89-6	0.754	1.15		11516	
wire	non noble metal	copper	7440-50-8	30.617	46.76	47.98	467608	479844
	non noble metal	copper	7440-50-8	0.773	1.18	1.18	11799	11799
	encapsulation	organic material	carbon black	1333-86-4	0.084	0.13		1282
	plastics	epoxy resin	-	3.274	5.00		50003	
	inorganic material	silicondioxide	60676-86-0	24.625	37.61	42.74	376092	427377
leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25072	25072
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12463	12463
glue	plastics	epoxy resin	-	0.114	0.17		1745	
	noble metal	silver	7440-22-4	0.539	0.82	0.99	8227	9972
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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